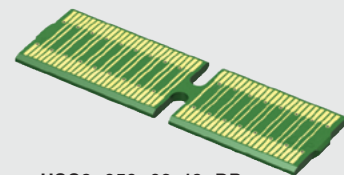


RU8-160-25-SE-L-DV-BL



HSC8-050-02-19-DP

(0.80 mm) .0315"

RU8, HSC8 SERIES

HIGH-SPEED RISER CARD KIT

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?RU8

CONNECTOR

Insulator Material:

Black LCP

Contact:

BeCu

Plating:

Au or Sn over

50 μm (1.27 μm) Ni

Current Rating:

3.1 A per pin

(6 adjacent pins powered)

Operating Temp:

-55 °C to +125 °C

**EDGE
RATE[®]**
CONTACT

Kit contains two connectors and one card. Assembly required.

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (40-60)

RoHS Compliant:

Yes

RECOGNITIONS

For complete scope of

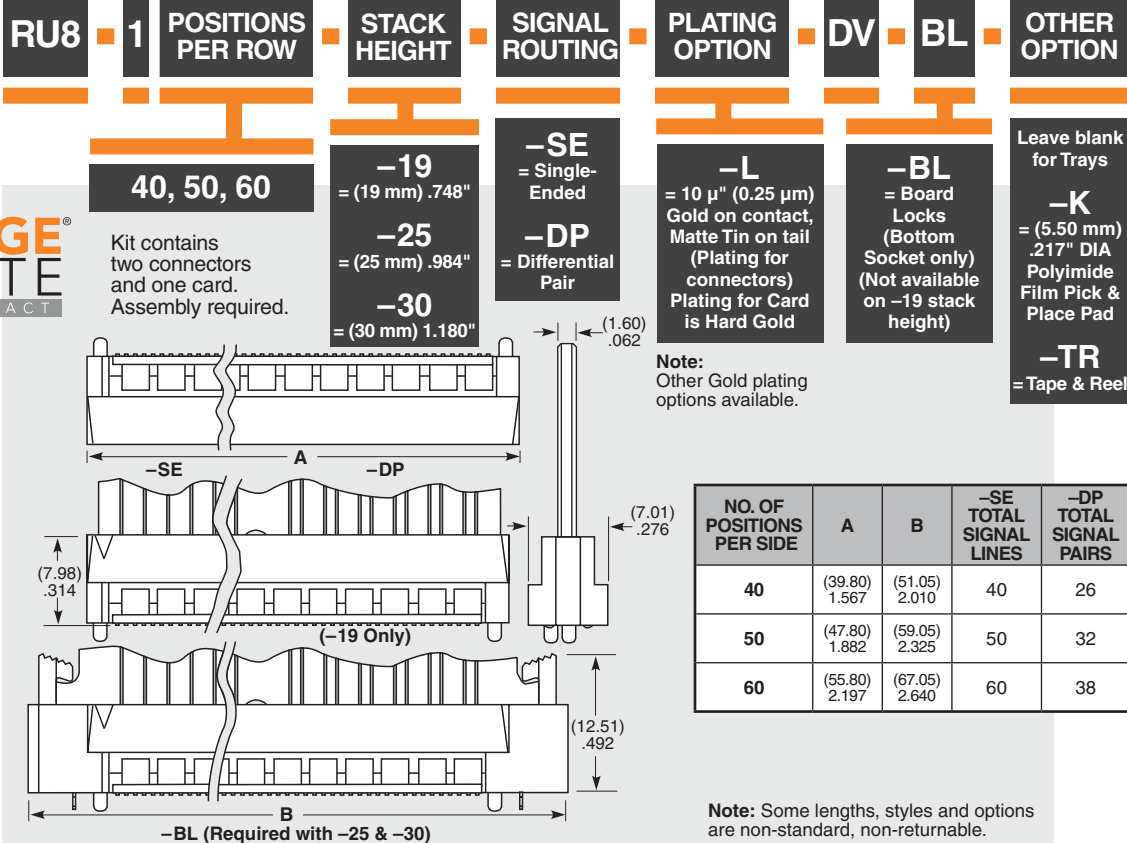
recognitions see

www.samtec.com/quality



Note:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.



Mates with:

HSEC8

SPECIFICATIONS

For complete specifications see www.samtec.com?HSC8

Conductor:

1/2 oz Copper

Contact Area:

Hard Gold Plated

Insulator: FR-4

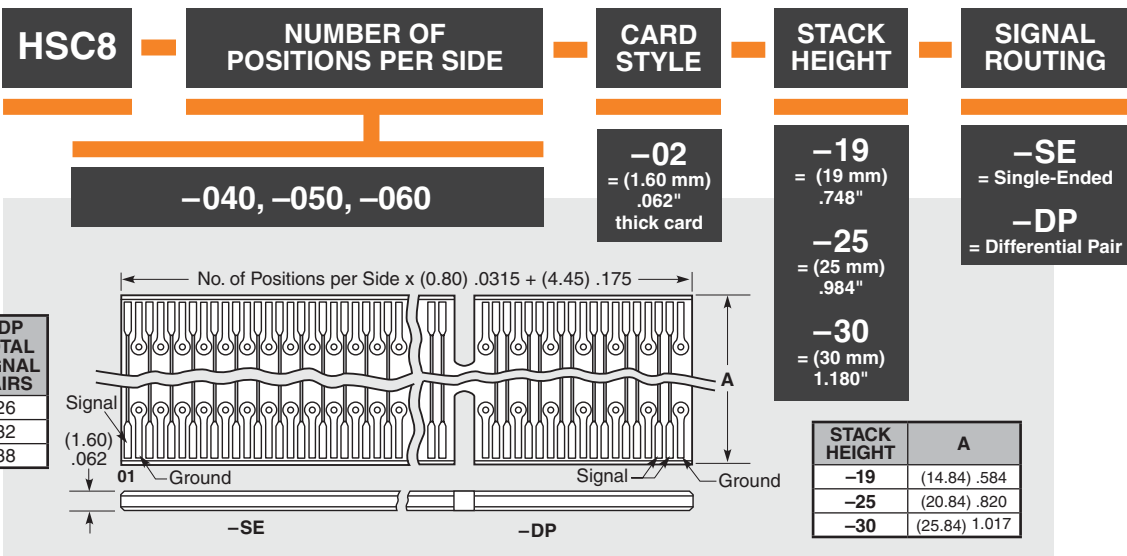
RoHS Compliant:

Yes

NO. OF POSITIONS PER SIDE	-SE TOTAL SIGNAL LINES	-DP TOTAL SIGNAL PAIRS
-40	40	26
-50	50	32
-60	60	38

Note:

Some sizes, styles and options are non-standard, non-returnable.



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.